



Features

- High speed 10MBit/s
- High isolation voltage between input and output (Viso=3750 Vrms)
- Guaranteed CTR performance from 0°C to 70°C
- Wide operating temperature range of -55°C to 100°C
- Green Package
- Regulatory Approvals
 - UL - UL1577 (Pending Approval)
 - VDE - EN60747-5-5 (Pending Approval)
 - CQC – GB4943.1, GB8898 (Pending Approval)
 - IEC60065, IEC60950 (Pending Approval)

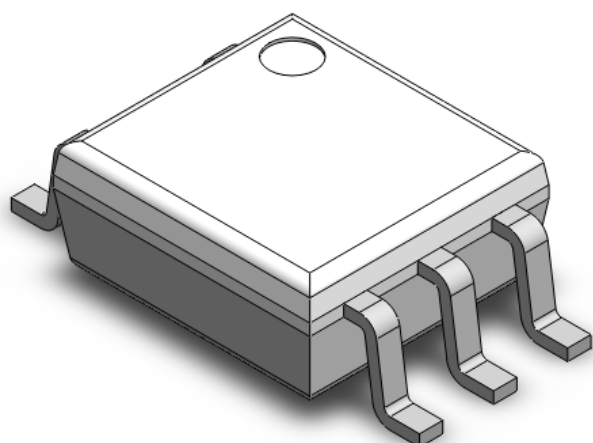
Description

The CTM410 optocouplers consist of an AlGaAs LED, optically coupled to a very high speed integrated photo-detector logic gate with a strobe able output. The output of the detect IC is a high speed logic gate integrated with a photo detector. The switching parameters are guaranteed over the temperature range of -40°C to +85°C. A maximum input signal of 5mA will provide a minimum output sink current of 13mA (fan out of 8).

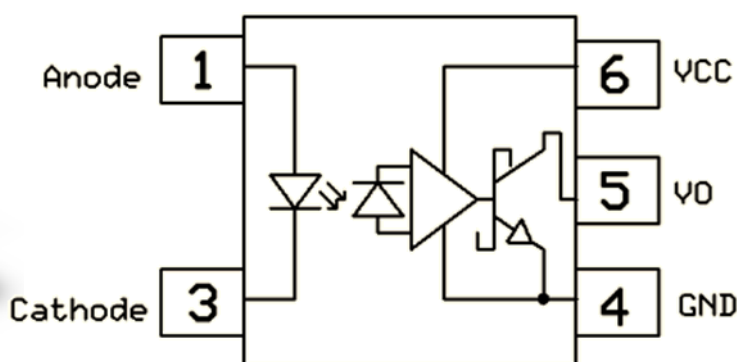
Applications

- Line receivers
- Telecommunication equipment
- High speed logic ground isolation
- Feedback loop in switch-mode power supplies
- Home appliances

Package Outline



Schematic



Note: Different bending options available. See package dimension.

**Absolute Maximum Rating at 25°C**

Symbol	Parameters	Ratings	Units	Notes
V _{ISO}	Isolation voltage	3750	V _{RMS}	1
T _{OPR}	Operating temperature	-55 ~ + 100	°C	
T _{STG}	Storage temperature	-55 ~ +150	°C	
T _{SOL}	Soldering temperature	260	°C	2
Emitter				
I _F	Forward current	50	mA	
V _R	Reverse voltage	5	V	
P _D	Power dissipation	100	mW	
Detector				
P _D	Power dissipation	85	mW	
I _O	Average Output current	50	mA	
V _{CC}	Supply voltage	7	V	
V _O	Output voltage	7	V	

Notes

1. AC for 1 minute, RH = 40 ~ 60%.
2. For 10 second peak



Electrical Characteristics

$T_A = 0 - 70^\circ\text{C}$ (unless otherwise specified). Typical values are measured at $T_A = 25^\circ\text{C}$ and $V_{CC}=5\text{V}$

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V_F	Forward voltage	$I_F = 10\text{mA}$	-	1.4	1.6	V	
V_R	Reverse Voltage	$I_R = 5\mu\text{A}$	5.0	-	-	V	
$\Delta V_F/\Delta T_A$	Temperature coefficient of forward voltage	$I_F = 10\text{mA}$	-	-1.6	-	mV/°C	

Detector Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
I_{CCL}	Logic Low Supply Current	$I_F=10\text{mA}$, $V_O=\text{Open}$, $V_{CC}=5\text{V}$	-	9	13	mA	
I_{CCH}	Logic High Supply Current	$I_F=0\text{mA}$, $V_O=\text{Open}$, $V_{CC}=5\text{V}$	-	6	10	mA	
R_{IO}	Isolation Resistance	$V_{IO}= 500\text{V}_{DC}$	5×10^{10}	-	-	Ω	
C_{IO}	Isolation Capacitance	$f= 1\text{MHz}$	-	0.5	1.2	pF	

Transfer Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
I_{OH}	Logic High Output Current	$I_F=250\mu\text{A}$, $V_O= 5.5\text{V}$,		2	100	μA	
I_{FT}	Input Threshold Current	$V_{CC}=5.5\text{V}$, $V_O=0.6\text{V}$, $I_O=13\text{mA}$	-	3.3	5	mA	
V_{OL}	Logic Low Output Voltage	$I_F=5\text{mA}$, $I_O=13\text{mA}$, $V_{CC}=5.5\text{V}$	-	0.35	0.6	V	

**Switching Characteristics**

<i>Symbol</i>	<i>Parameters</i>	<i>Test Conditions</i>	<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Units</i>	<i>Notes</i>
T_{PHL}	Propagation Delay Time Logic High to Logic Low	$C_L=15pF, R_L=350\Omega$	-	40	75	ns	
T_{PLH}	Propagation Delay Time Logic Low to Logic High		-	35	75	ns	
T_r	Output Rise Time		-	40	-	ns	
T_f	Output Fall Time		-	10	-	ns	
CM_H	Common Mode Transient Immunity at Logic High	$I_F = 7.5mA, V_{OH}=2.0V, R_L=350\Omega, T_A=25^\circ C, V_{CM}=1000Vp-p$	10000	-	-	V/ μs	
CM_L	Common Mode Transient Immunity at Logic Low	$I_F = 0mA, V_{OL}=0.8V, R_L=350\Omega, T_A=25^\circ C, V_{CM}=1000Vp-p$	10000	-	-	V/ μs	



Typical Characteristic Curves

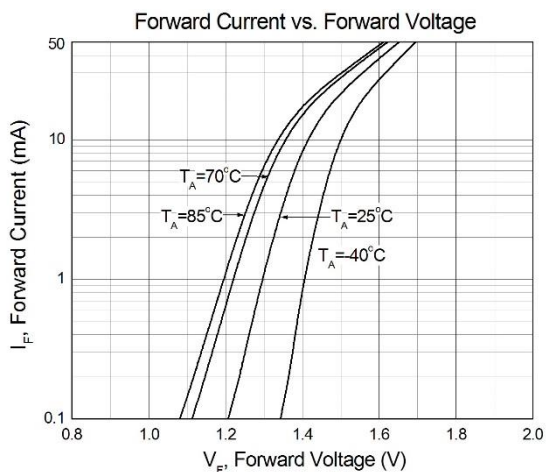


Figure 1

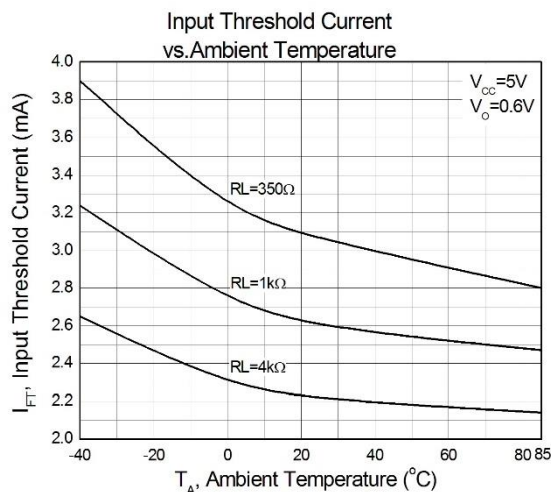


Figure 2

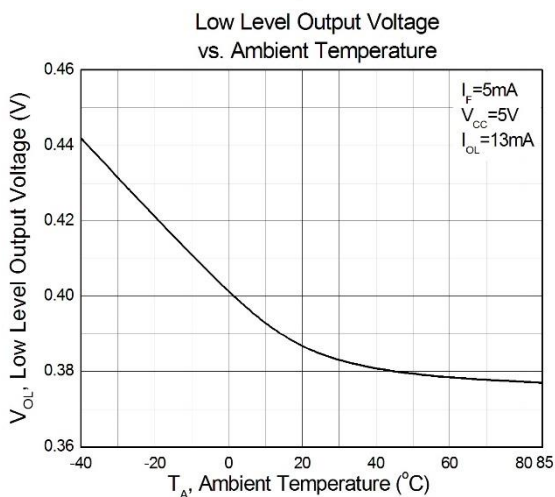


Figure 3

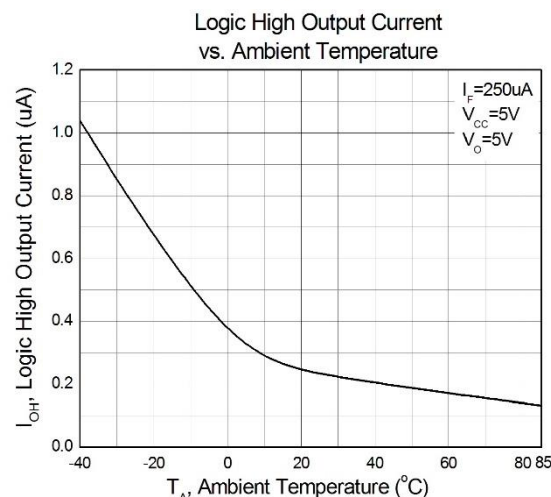


Figure 4

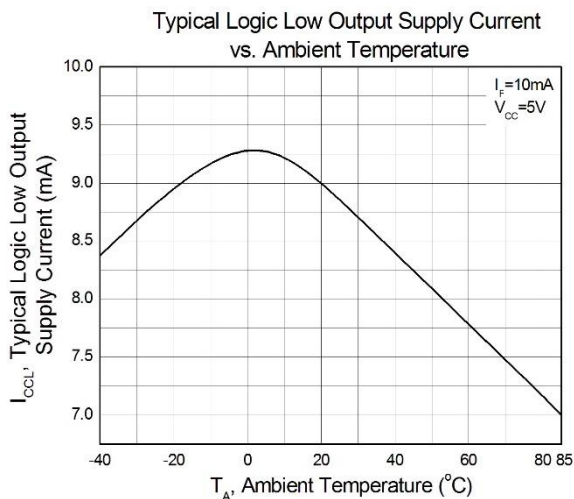


Figure 5

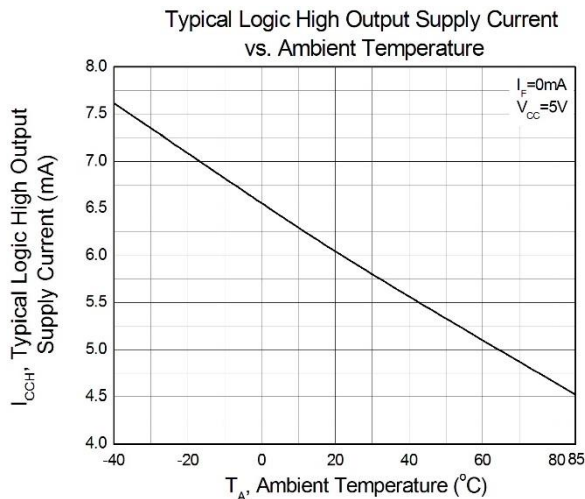


Figure 6



10Mbit/s 5-Pin Mini-Flat Logic Gate Optocoupler

Typical Logic Output Supply Current vs. Output Supply Voltage

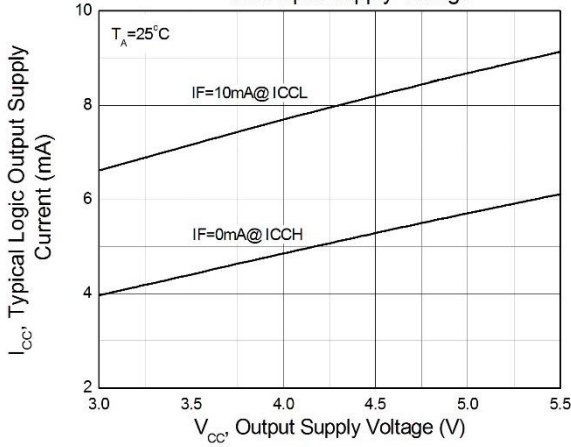


Figure 7

Propagation Delay vs. Ambient Temperature

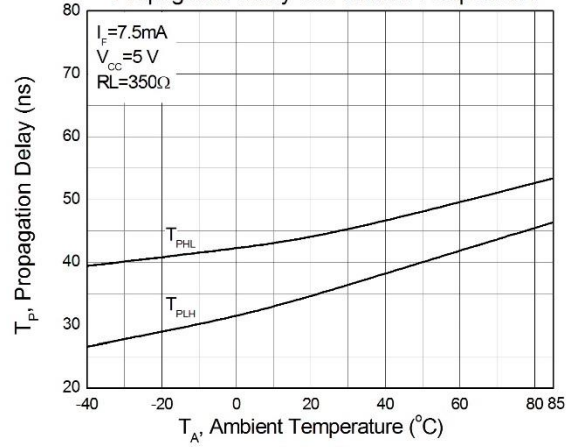


Figure 8

Pulse Width Distortion vs. Ambient Temperature

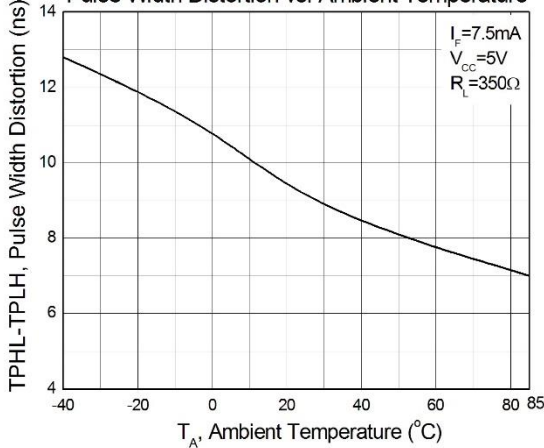


Figure 9

Rise And Fall Time vs. Ambient Temperature

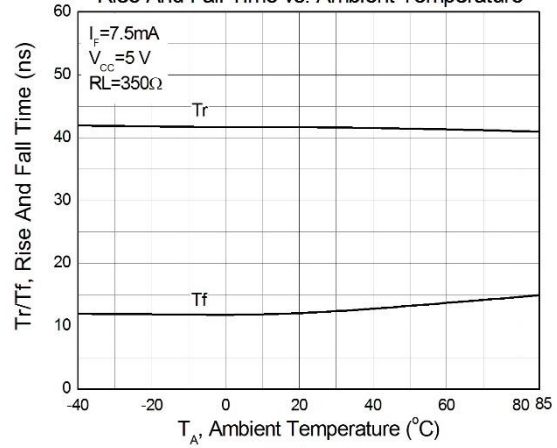


Figure 10

PULSE WIDTH DISTORTION vs. Ambient Temperature

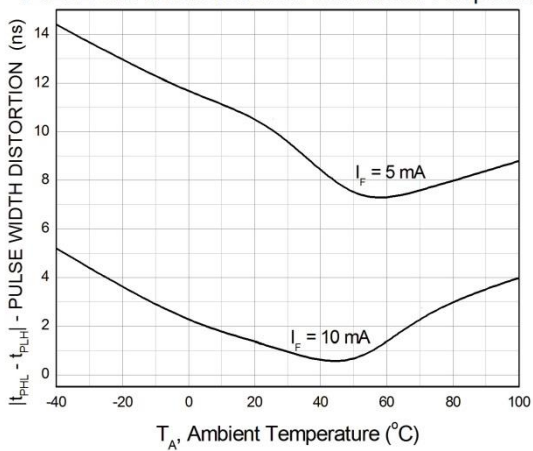


Figure 11



Test Circuits

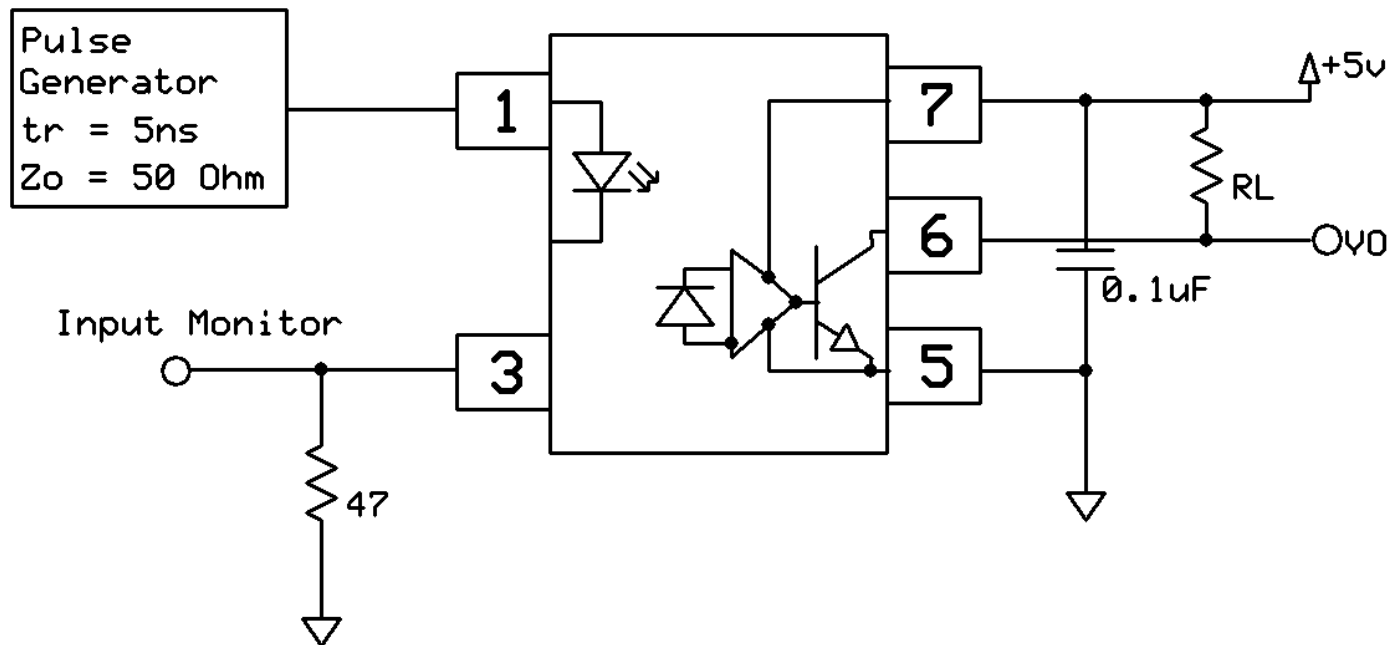


Figure 11

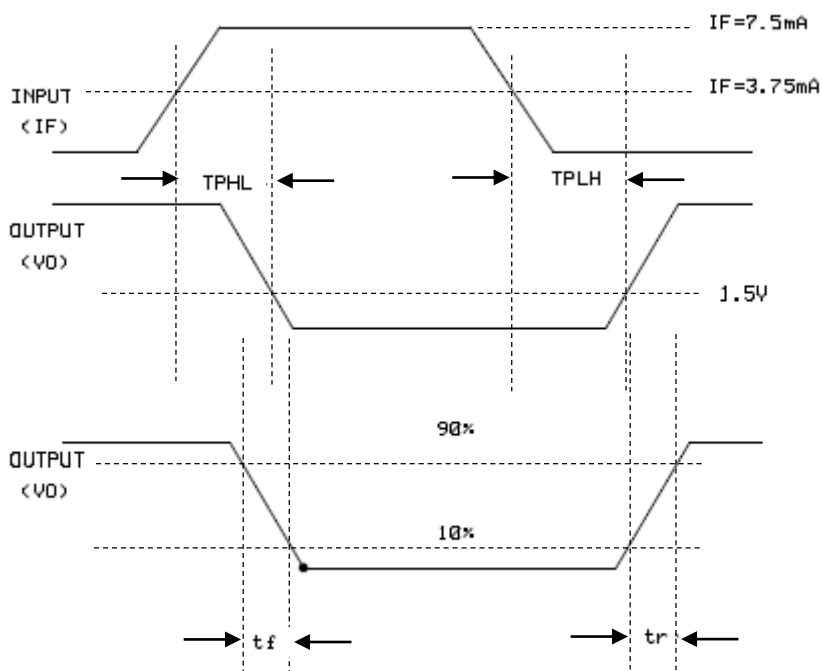


Figure 12



Test Circuits

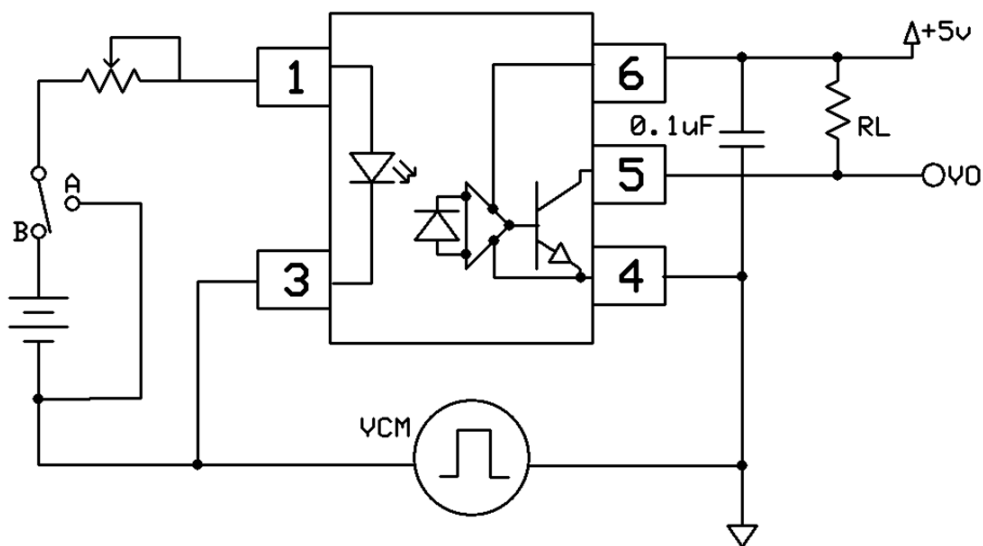
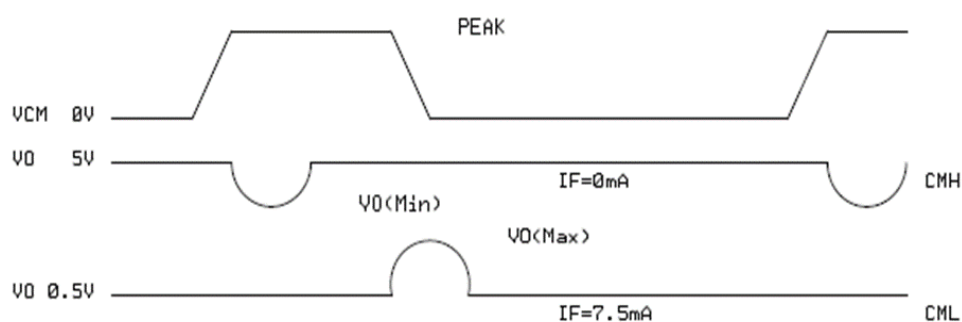


Figure 13

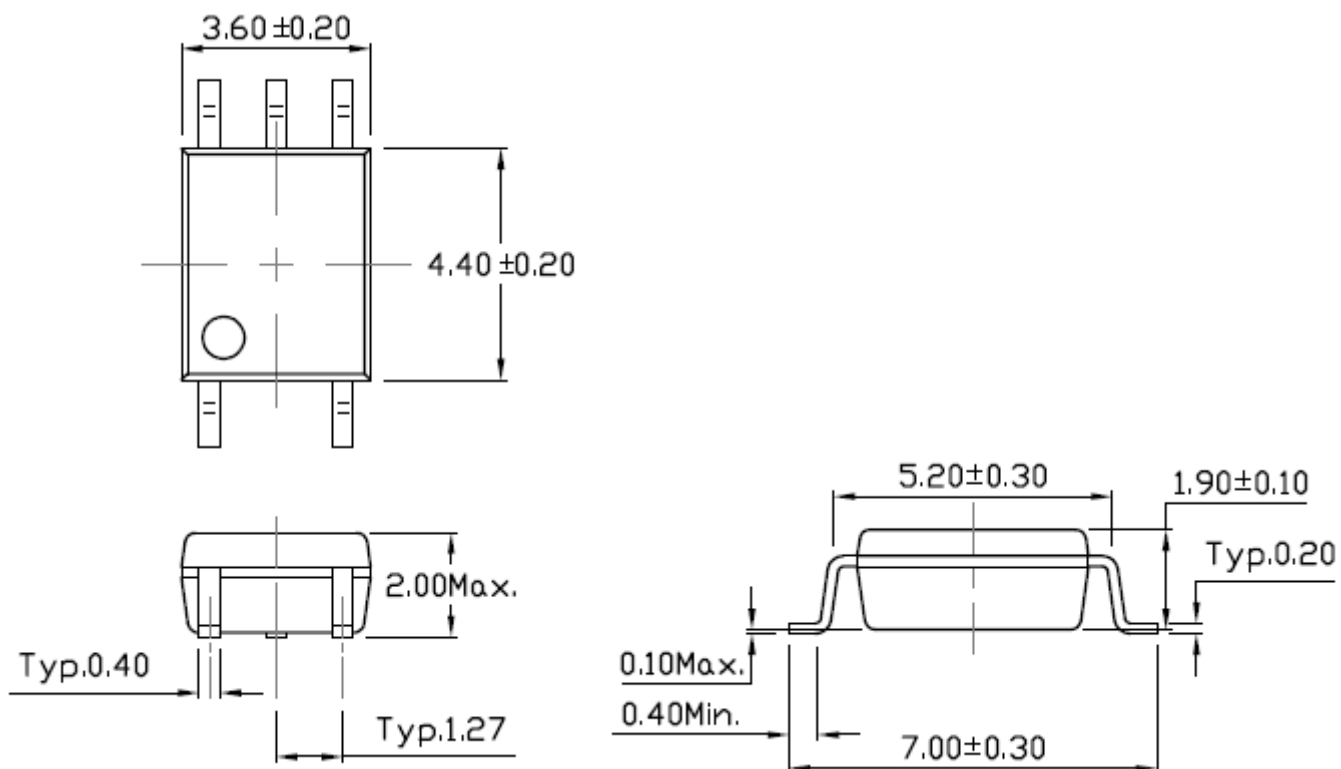


CMR Test Circuit

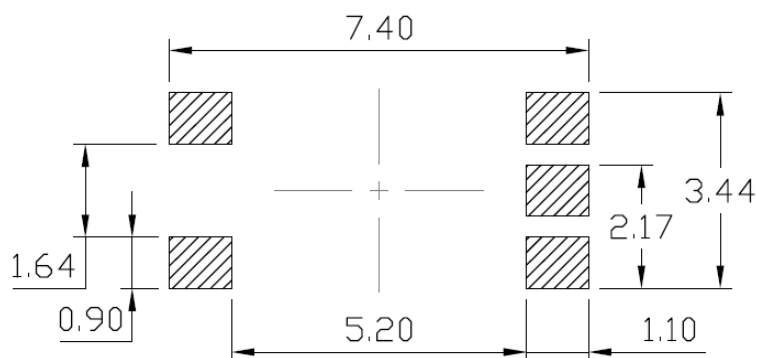
Figure 14



Package Dimension *Dimensions in mm unless otherwise stated*



Recommended Solder Mask *Dimensions in mm unless otherwise stated*





Device Marking



Note:

- CT : Denotes “CT Micro”
- M410 : Product Number
- V : VDE Option (V or none)
- Y : Fiscal Year
- WW : Work Week
- K : Production Code

Ordering Information

CTM410(V)(Y)

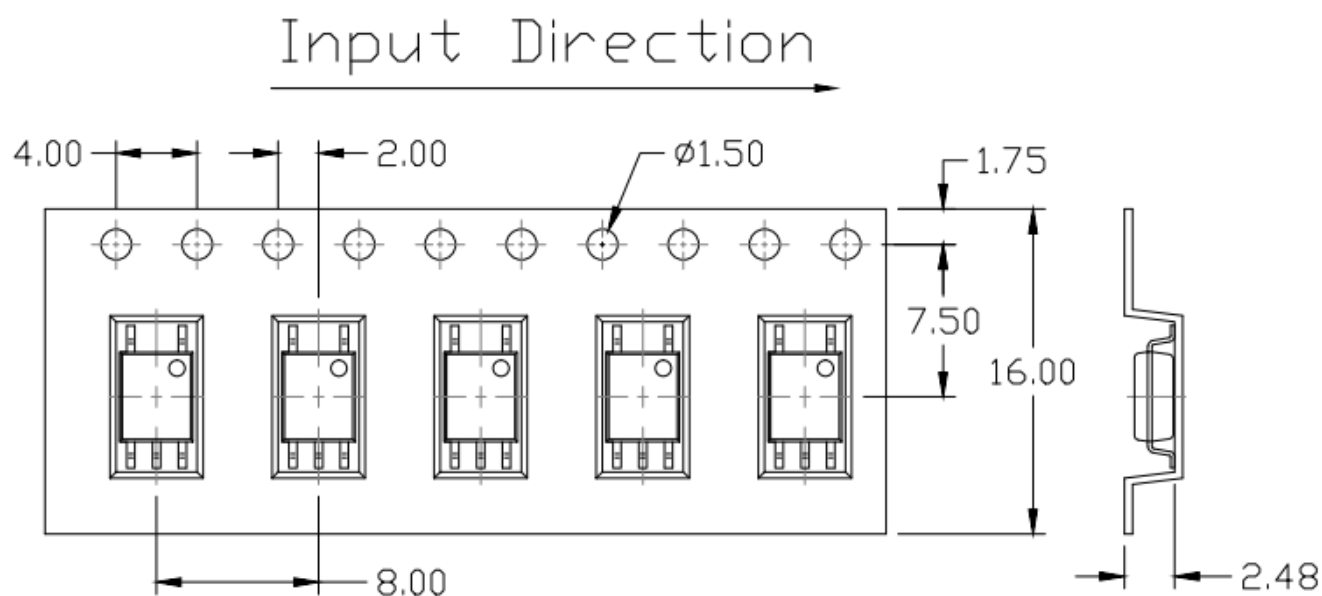
- CT : Denotes “CT Micro”
- M410 : Part Number
- V : VDE Safety Option (V or none)
- Y : Tape and reel option (T1or T2)

Option	Description	Quantity
T1	Surface Mount Lead Forming – With Option 1 Taping	3000 Units/Reel
T2	Surface Mount Lead Forming – With Option 2 Taping	3000 Units/Reel

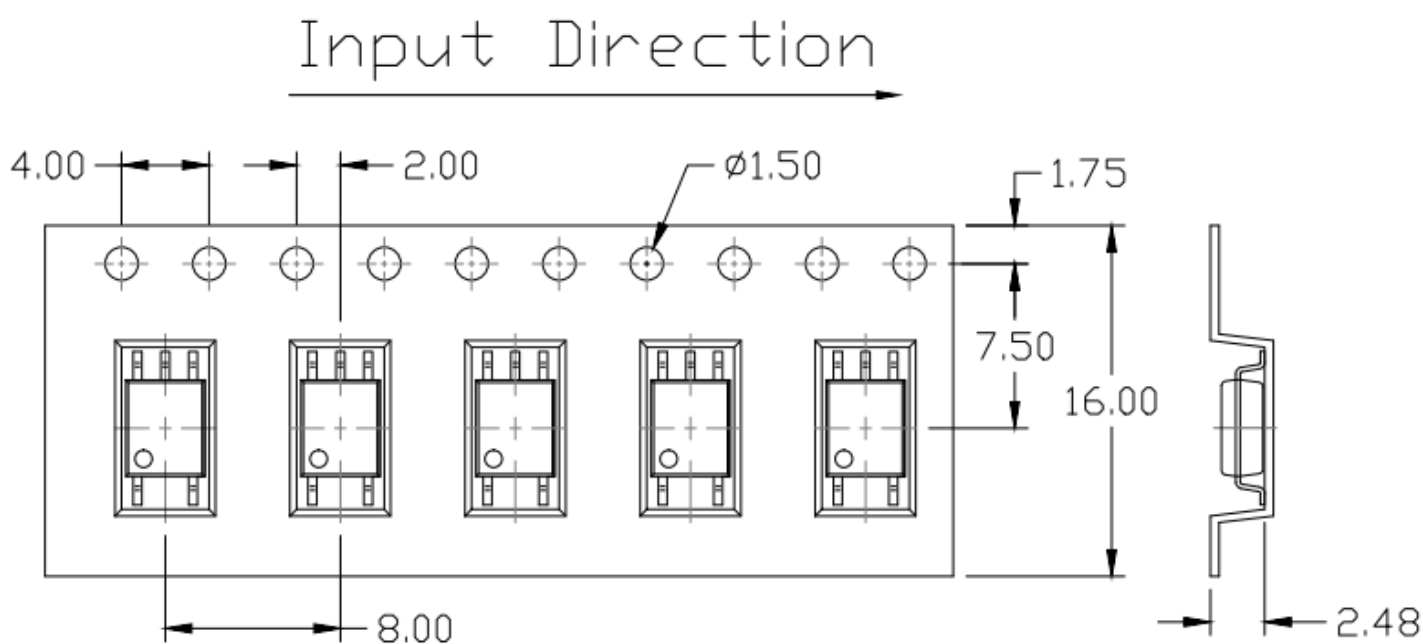


Carrier Tape Specifications *Dimensions in mm unless otherwise stated*

Option T1

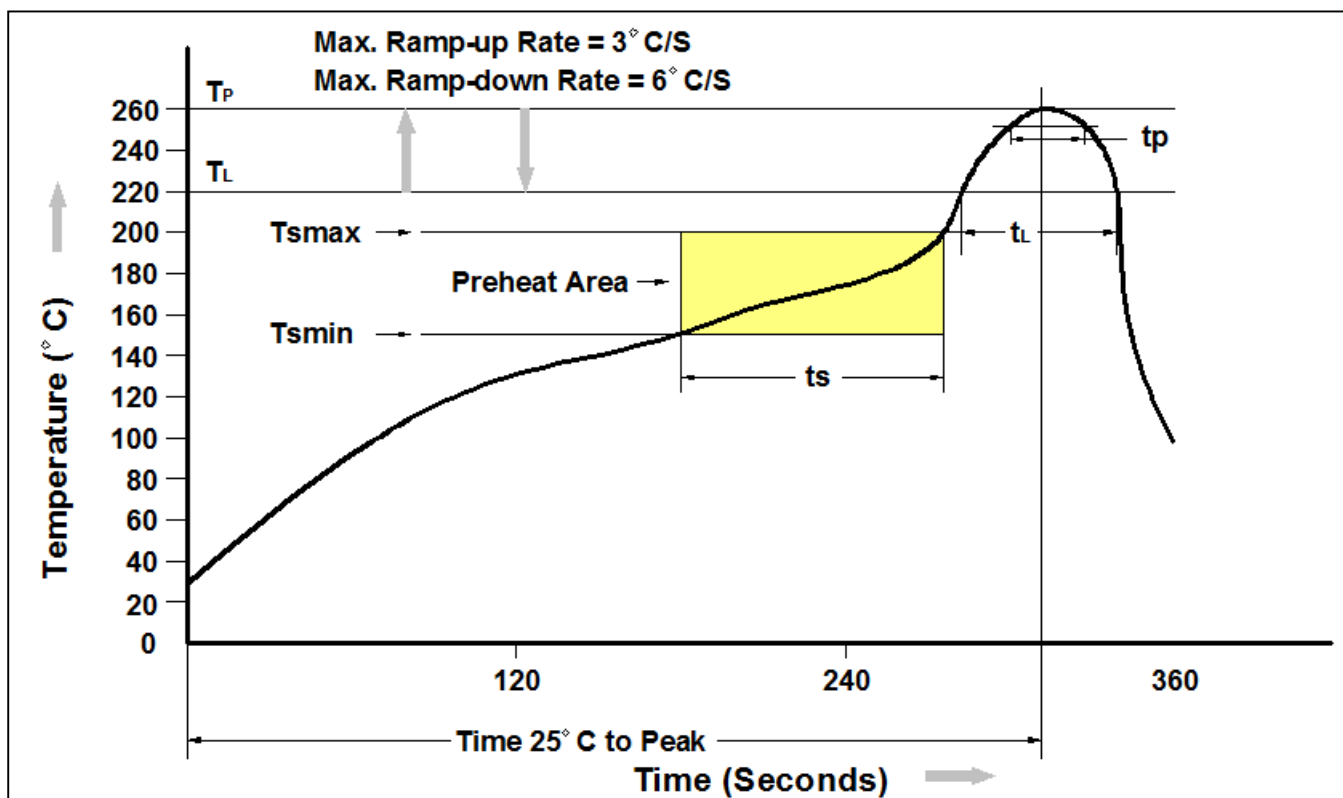


Option T2





Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	150°C
Temperature Max. (T _{smax})	200°C
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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